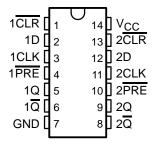
- EPIC[™] (Enhanced-Performance Implanted CMOS) 2-µ Process
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC}, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 > 2 V at V_{CC}, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Package Options Include Plastic Small-Outline (D), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), Ceramic Flat (W) Packages, Chip Carriers (FK), and (J) 300-mil DIPs

description

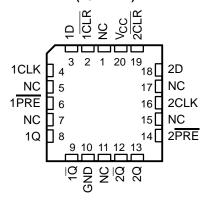
These dual positive-edge-triggered D-type flip-flops are designed for 2.7-V to 5.5-V $\rm V_{CC}$ operation.

A low level at the preset (PRE) or clear (CLR) inputs sets or resets the outputs regardless of the levels of the other inputs. When PRE and CLR are inactive (high), data at the data (D) inputs meeting the setup-time requirements is transferred to the

SN54LV74...J OR W PACKAGE SN74LV74...D, DP, OR PW PACKAGE (TOP VIEW)



SN54LV74 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

outputs on the positive-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the D input can be changed without affecting the levels at the outputs.

The SN74LV74 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54LV74 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LV74 is characterized for operation from –40°C to 85°C.



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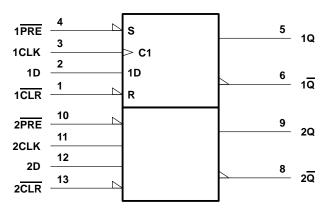


FUNCTION TABLE

	INP	UTS		OUTI	PUTS
PRE	CLR	CLK	D	Q	Ø
L	Н	Х	Χ	Н	L
Н	L	X	Χ	L	Н
L	L	X	Χ	н†	H [†]
Н	Н	\uparrow	Н	Н	L
Н	Н	\uparrow	L	L	Н
Н	Н	L	Χ	Q ₀	\overline{Q}_0

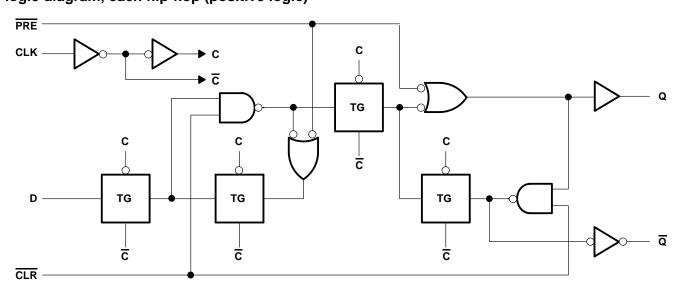
[†] This configuration is nonstable; that is, it does not persist when PRE or CLR returns to its inactive (high) level.

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, DB, J, PW, and W packages.

logic diagram, each flip-flop (positive logic)





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Output voltage range, VO (see Notes 1 and 2)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3	3): D package1.25 W
	DB or PW package 0.5 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 7 V maximum.
 - 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 4)

			SN54I	_V74	SN74	UNIT	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		2.7	5.5	2.7	5.5	V
V	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		2		٧
VIH	riigii-ievei iriput voitage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	3.15		3.15		V
V	V _{CC} = 2			0.8		0.8	V
VIL	Low-level input voltage	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		1.65		1.65	V
٧ _I	Input voltage		0 4	VCC	0	VCC	٧
٧o	Output voltage		0	VCC	0	VCC	V
lou	High-level output current	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	20	-6		-6	mA
ЮН	riigii-ievei output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	Po	-12		-12	IIIA
lo:	Low level output ourrent	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	Y	6		6	mA
IOL	Low-level output current	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12	IIIA
Δt/Δν	Input transition rise or fall rate		0	100	0	100	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEOT 00	NOTIONS	,, +	SI	N54LV7	4	SI	N74LV74	4	
PARAMETER	I EST CO	NDITIONS	v _{cc} †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	I _{OH} = -100 μA		MIN to MAX	VCC - 0).2		VCC - C).2		
Voн	I _{OH} = -6 mA		3 V	2.4			2.4			V
	I _{OH} = -12 mA		4.5 V	3.6			3.6			
	I _{OL} = 100 μA		MIN to MAX			0.2			0.2	
VoL	$I_{OL} = 6 \text{ mA}$	I _{OL} = 6 mA			7/	0.4			0.4	V
	I _{OL} = 12 mA		4.5 V		9/5	0.55			0.55	
1.	V _I = V _{CC} or GND		3.6 V		7	±1			±1	μΑ
lι	AL = ACC OL GIAD	AI = ACC OL GND			5	±1			±1	μΑ
loo	VI – Voe or CND	IO = 0	3.6 V	0)	20			20	
lcc	VI = VCC or GND	IQ = 0	5.5 V	6		20			20	μΑ
ΔICC	One input at V _{CC} – 0.6 V	Other inputs at V _{CC} or GND	3 V to 3.6 V			500			500	μА
C.	V. V or CND	_	3.3 V		2.5			2.5		٠,
C _i	$V_I = V_{CC}$ or GND		5 V		3			3		pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			V _{CC} :		V _{CC} = ± 0.		V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		0	70	0	60	0	50	ns
	Pulse duration, LE high	PRE or CLR low	15		20		25		ns
t _W	Fulse duration, LE mgn	CLK high or low	15	ODI	20	~	25		115
	Catura tima a data hafana CLIVA	Data	6	PRO	8	PRO	12		20
t _{su}	Setup time, data before CLK↑	PRE or CLR inactive	5	6/4	6	<	8		ns
th	Hold time, data after CLK↑		3		3		3		ns

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

				= 5 V 5 V	V _{CC} =		V _{CC} =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency		0	70	0	60	0	50	ns
	Pulse disserting LE blok	PRE or CLR low	15		20		25		ns
t _W	Pulse duration, LE high	CLK high or low	15		20		25		115
	Catura time a data hafara CLIVA	Data	6		8		12		no
t _{su}	Setup time, data before CLK↑	PRE or CLR inactive	5		6		8		ns
th	Hold time, data after CLK↑		3		3		3		ns

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

						SN54	4LV74				
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} :	= 5 V ±	0.5 V	VCC =	3.3 V ±	0.3 V	V _{CC} =	2.7 V	UNIT
	(01)	(0011 01)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX	
f _{max}			70	100	20170	60	90	201	50		MHz
t _{and}	PRE or CLR	Q or Q		11,	19		18	27	7/1	34	ns
^t pd	CLK	QUIQ		10	17		17	26		28	113

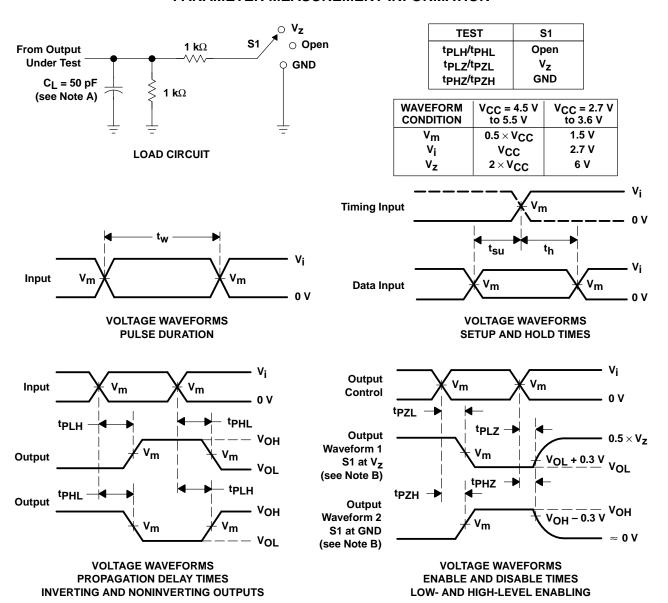
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER						SN74	LV74				
	FROM (INPUT)	TO (OUTPUT)	VCC =	= 5 V ±	0.5 V	VCC =	3.3 V ±	0.3 V	VCC =	= 2.7 V	UNIT
	(01)	(0011 01)	MIN	TYP	MAX	MIN	TYP	MAX	MIN	MAX	
f _{max}			70	100		60	90		50		MHz
† .	PRE or CLR	Q or Q		11	19		18	27		34	ns
^t pd	CLK	QuQ		10	17		17	26		28	113

operating characteristics, T_A = 25°C

	PARAMETER	TEST CONDITIONS	VCC	TYP	UNIT
C . Down discinsting consistence monthly flag	C ₁ = 50 pF. f = 10 MHz	3.3 V	32	pF	
Cpd	Power dissipation capacitance per flip-flop	$C_L = 50 \text{ pF}, \qquad f = 10 \text{ MHz}$	5 V	68	pr

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2.5 \ ns$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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